

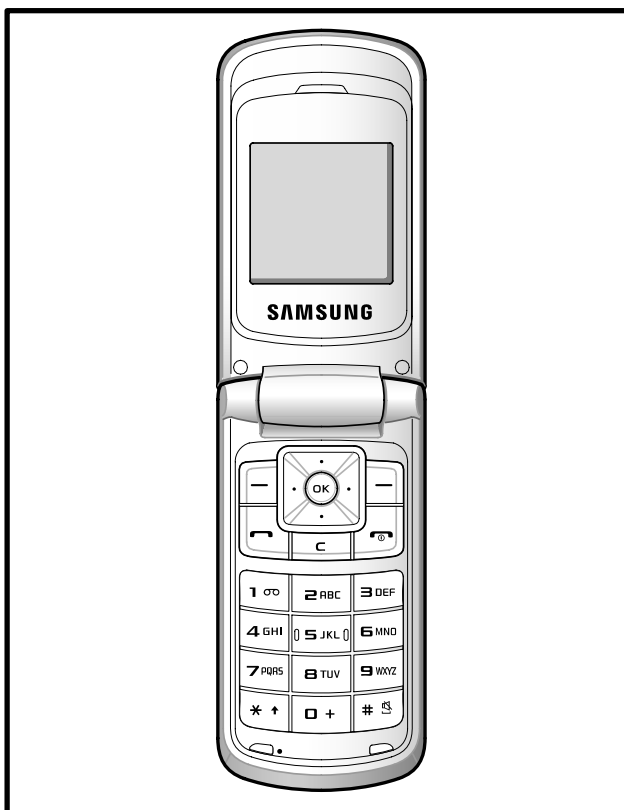
SAMSUNG

GSM TELEPHONE

SGH-B300

SERVICE *Manual*

GSM TELEPHONE



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**SAMSUNG
ELECTRONICS**



GSPN (Global Service Partner Network)

Country	Web Site
North America	service.samsungportal.com
Latin America	latin.samsungportal.com
CIS	cis.samsungportal.com
Europe	europa.samsungportal.com
China	china.samsungportal.com
Asia	asia.samsungportal.com
Mideast & Africa	mea.samsungportal.com

2. Specification

2-1. GSM General Specification

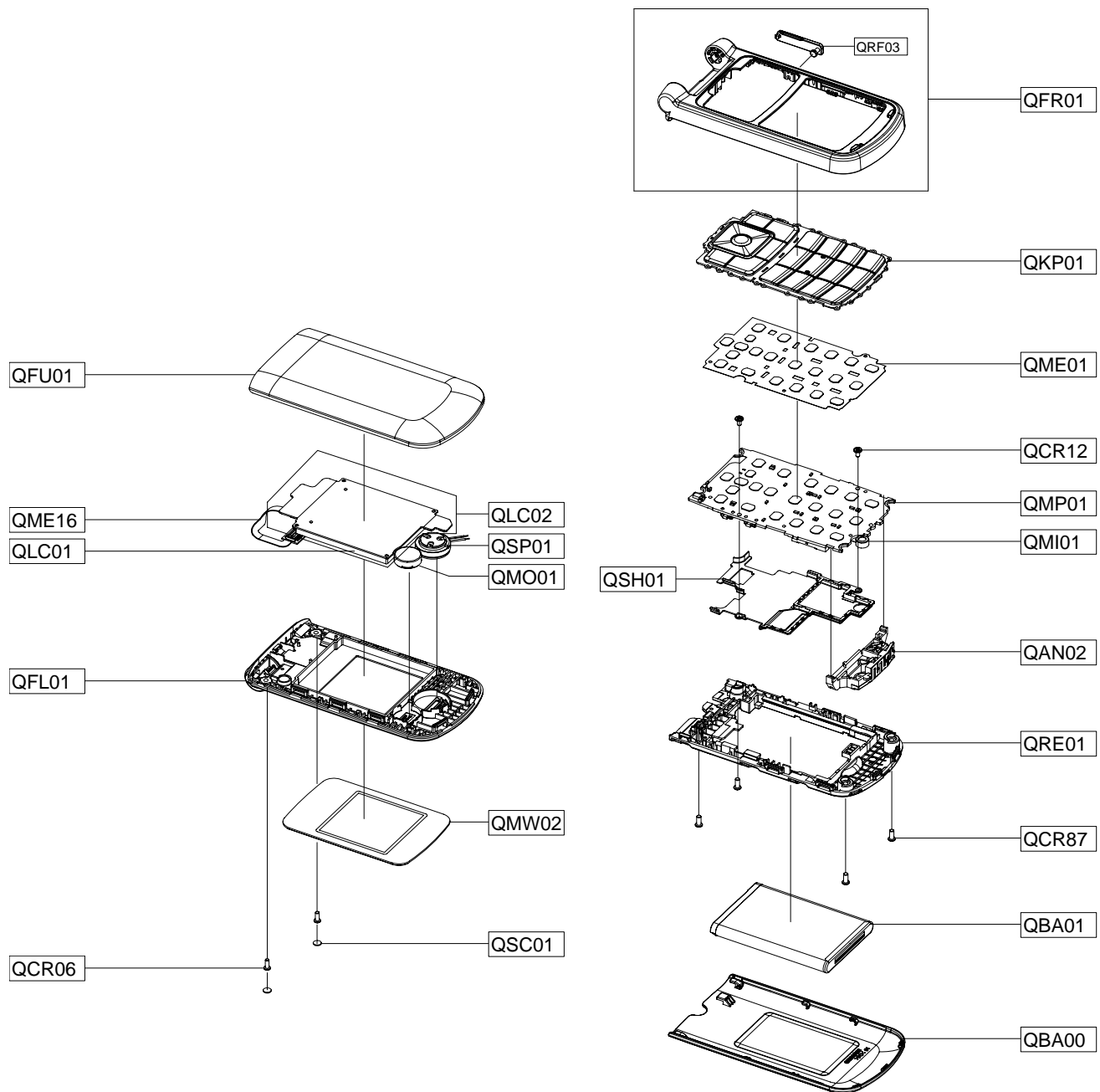
	EGSM 900 Phase 2	DCS1800 Phase 1
Freq. Band[MHz] Uplink/Downlink	880~915 925~960	1710~1785 1805~1880
ARFCN range	0~124 & 975~1023	512~885
Tx/Rx spacing	45 MHz	95 MHz
Mod. Bit rate/ Bit Period	270.833 kbps 3.692 us	270.833 kbps 3.692 us
Time Slot Period/Frame Period	576.9 us 4.615 ms	576.9 us 4.615 ms
Modulation	0.3 GMSK	0.3 GMSK
MS Power	33 dBm~5 dBm	30 dBm~0 dBm
Power Class	5 pcl ~ 19 pcl	0 pcl ~ 15 pcl
Sensitivity	-102 dBm	-100 dBm
TDMA Mux	8	8
Cell Radius	35 Km	2 Km

2-2. GSM Tx Power Class

TX Power control level	GSM900	TX Power control level	DCS1800
5	33±2 dBm	0	30±3 dBm
6	31±2 dBm	1	28±3 dBm
7	29±2 dBm	2	26±3 dBm
8	27±2 dBm	3	24±3 dBm
9	25±2 dBm	4	22±3 dBm
10	23±2 dBm	5	20±3 dBm
11	21±2 dBm	6	18±3 dBm
12	19±2 dBm	7	16±3 dBm
13	17±2 dBm	8	14±3 dBm
14	15±2 dBm	9	12±4 dBm
15	13±2 dBm	10	10±4 dBm
16	11±3 dBm	11	8±4 dBm
17	9±3 dBm	12	6±4 dBm
18	7±3 dBm	13	4±4 dBm
19	5±3 dBm	14	2±5 dBm
		15	0±5 dBm

5. Exploded View and Parts List

5-1. Cellular phone Exploded View


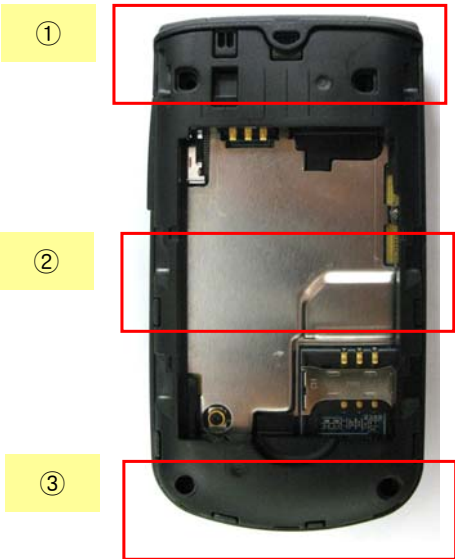
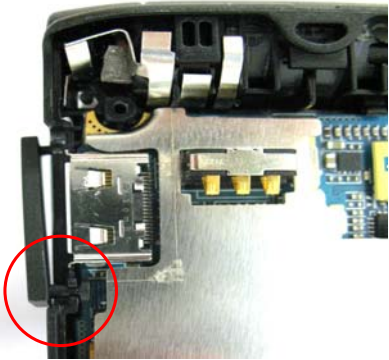
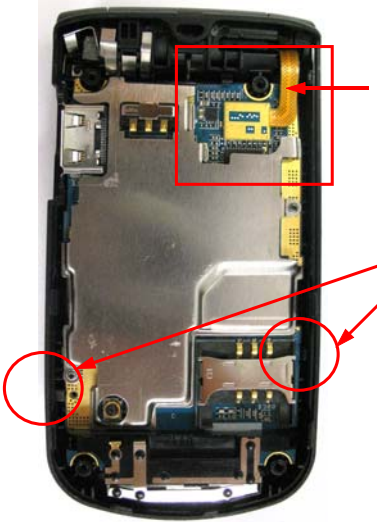


5-2. Cellular phone Parts list

Design LOC		Discription	SEC CODE
QAN02		INTENNA-SGHB300	GH42-01534A
QBA00		PMO COVER-BATTERY	GH72-46670A
QBA01		INNER BATTERY PACK-750MAH,BLK,	GH43-02483A
QCR06		SCREW-MACHINE	6001-001155
QCR12		SCREW-MACHINE	6001-001530
QCR87		SCREW-TAPPING	6002-001412
QFL01		ASSY CASE-LOWER	GH98-07688A
QFU01		ASSY CASE-UPPER	GH98-07689A
QKP01		ASSY KEYPAD-(XEF/DGA)	GH98-07671A
QLC01		LCD-MODULE SGHB110L	GH07-01241A
QLC02		ELA UNIT-SGHB300 LCD MODULE SV	GH96-03067A
QME01		DOME SHEET-SGHB300	GH59-05506A
QME16		UNIT-SGHB300 CON TO CON	GH59-05509A
QMI01		MICROPHONE-ASSY-SGHB300	GH30-00467A
QMO01		MOTOR DC-SGHZ130	GH31-00154C
QMP01		PBA MAIN-SGHB300	GH92-04468A
QMW02		PMO WINDOW-MAIN	GH72-46665A
QRE01		ASSY CASE-REAR	GH98-07686A
QSC01		TAPE-COVER SCREW LOWER	GH74-38101A
QSH01		ASSY BRACKET-SHIELD CAN	GH98-07685A
QSP01		SPEAKER	3001-002344
QFR01		ASSY CASE-FRONT	GH98-07687A
	QRF03	PMO COVER-EAR	GH72-46664A

7. Disassembly and Assembly Instructions

7-1. Disassembly

<div data-bbox="147 268 215 317" data-label="Text">1</div> 	<div data-bbox="808 268 876 317" data-label="Text">2</div> 
<p>1) Release SCREW 4 POINT at Rear.</p> <p>※ Caution</p> <p>1) Be careful not to make scratch.</p>	<p>1) Disjoint HOOK from up to down.</p> <p>※ Caution</p> <p>1) Be careful Hook damage when you Disjoint a REAR.</p>
<div data-bbox="147 1094 215 1142" data-label="Text">3</div>  <div data-bbox="212 1444 370 1545" data-label="Text">IF COVER HOOK</div>	<div data-bbox="808 1094 876 1142" data-label="Text">4</div>  <div data-bbox="1252 1213 1409 1352" data-label="Text">LCD CONNECT OR</div> <div data-bbox="1252 1409 1409 1547" data-label="Text">PBA HOOK 2 POINT</div>
<p>1) Seperate the IF COVER front FRONT.</p>	<p>1) Disjoint LCD CONNECTOR.</p> <p>2) Separate PBA from FRONT.</p>

5



- 1) Put tweezers to Front hole and Press down a Hinge.
- 2) Separate FRONT and FOLDER ASS'Y during doing NO.1.

※ **Caution**

- 1) Beware that you do not damage LCD F-PCB.
- 2) Be careful that you do not make scratch when you press down a Hinge.

6



- 1) Remove SCREW CAP using tweezers.(2POINT)
- 2) Release SCREW.

※ **Caution**

- 1) Be careful not to make scratch and molding damage!

7

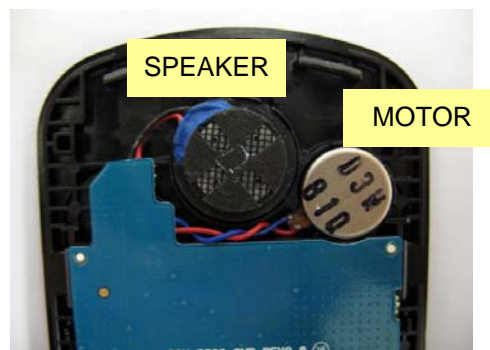


- 1) Separate UPPER from LOWER.
Release a HOOK which locate upside first.

※ **Caution**

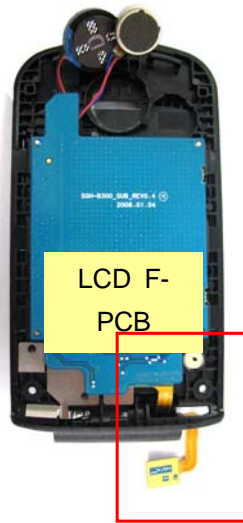
- 1) Be careful Hook damage when you disjoint a UPPER.

8



- 1) Separate MOTOR from the LOWER
- 2) Separate SPEAKER from the LOWER

9



1) Separate a Folder LOWER and LCD MODULE.

※ **Caution**

- 1) Beware that you do not damage LCD F-PCB.
- 2) Beware that you do not damage F-PCB when you passing F-PCB to hole of LOWER

7-2. Assembly

1

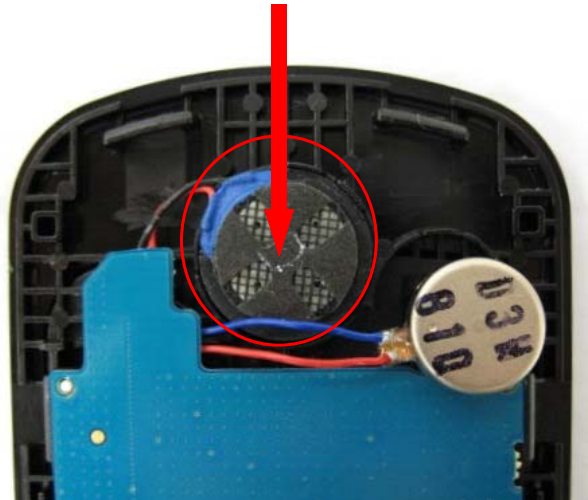


- 1) Put LCD F-PCB into the hole of LOWER.
- 2) Put LCD Ass'y in Folder Lower.

※ **Caution**

- 1) Be careful not to make scratch and molding damage.
- 2) Beware that you do not damage F-PCB when you insert F-PCB to hole of LOWER

2

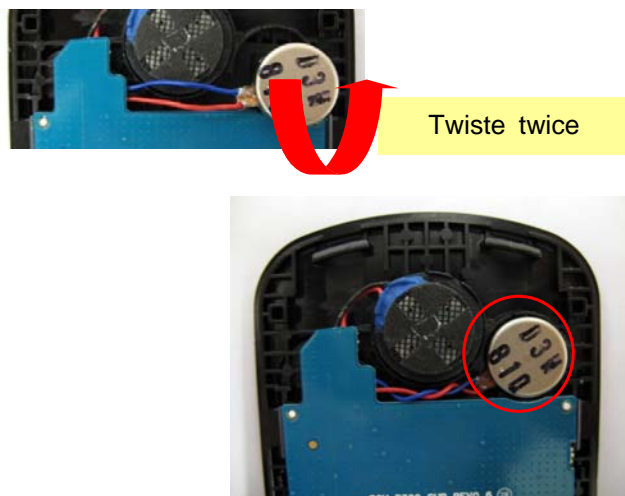


- 1) Put the SPEAKER on the UPPER

※ **Caution**

- 1) Arrange WIRE not to be interfered with other components.

3



- 1) Twist the MOTOR wire twice, then put into the LOWER

※ **Caution**

- 1) Arrange WIRE not to be interfered with other components.

4

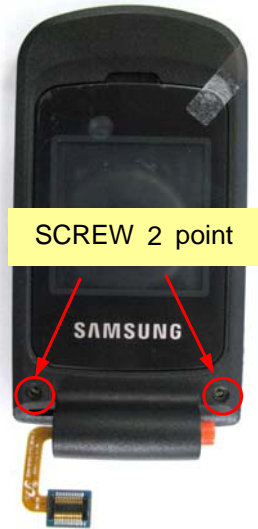


- 1) Assemble Folder Lower and Folder Upper from upside.

※ **Caution**

- 1) Be careful not to make scratch and molding damage.
- 2) Check GAP is exist after finish assembly.

5



- 1) Screw up two screws at FOLDER LOWER.
- 2) Put in screw caps.

※ **Caution**

- 1) Be careful not to make scratch and molding damage!

6



- 1) Insert F-PCB to hole of FRONT.
- 2) Assemble while pressing the hinge.

※ **Caution**

- 1) Beware that you do not damage F-PCB when you insert F-PCB to hole of FRONT
- 2) Open and close a folder 2~3 times to Check there is a problem or not.

7

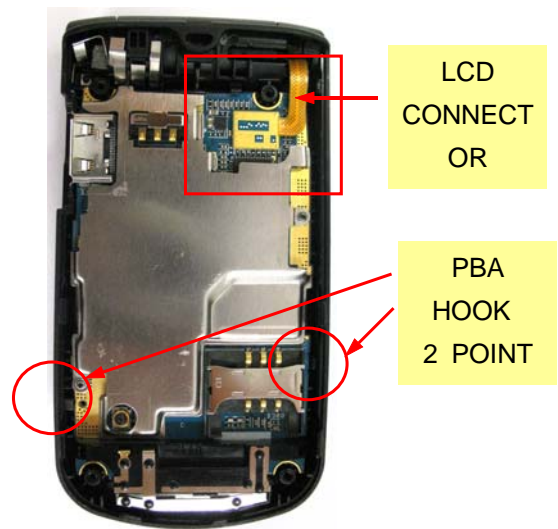


- 1) Set KEYPAD on the FRONT.

※ **Caution**

- 1) Check the KEYPAD's guide hole.

8

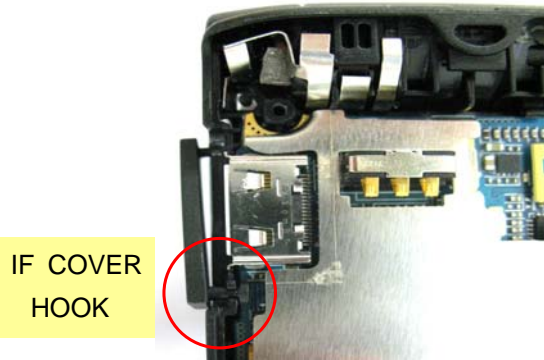


- 1) Set a PBA.
- 2) Connect RF CONNECTOR.

※ **Caution**

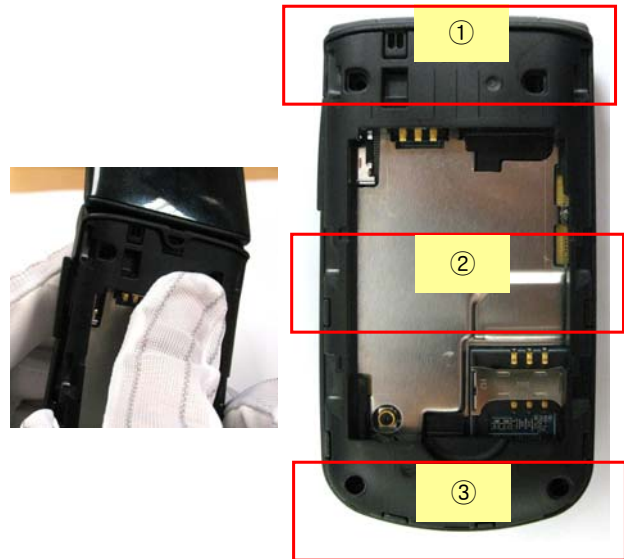
- 1) Be careful not to make scratch and molding damage!

9



1) Set the IF COVER on the FRONT.

10



1) Assemble REAR and FRONT ass'y from upside.

※ **Caution**

1) Be careful not to make scratch and molding damage!

2) Check GAP is exist after finish assembly.

11



1) Attach lower screw sheet.

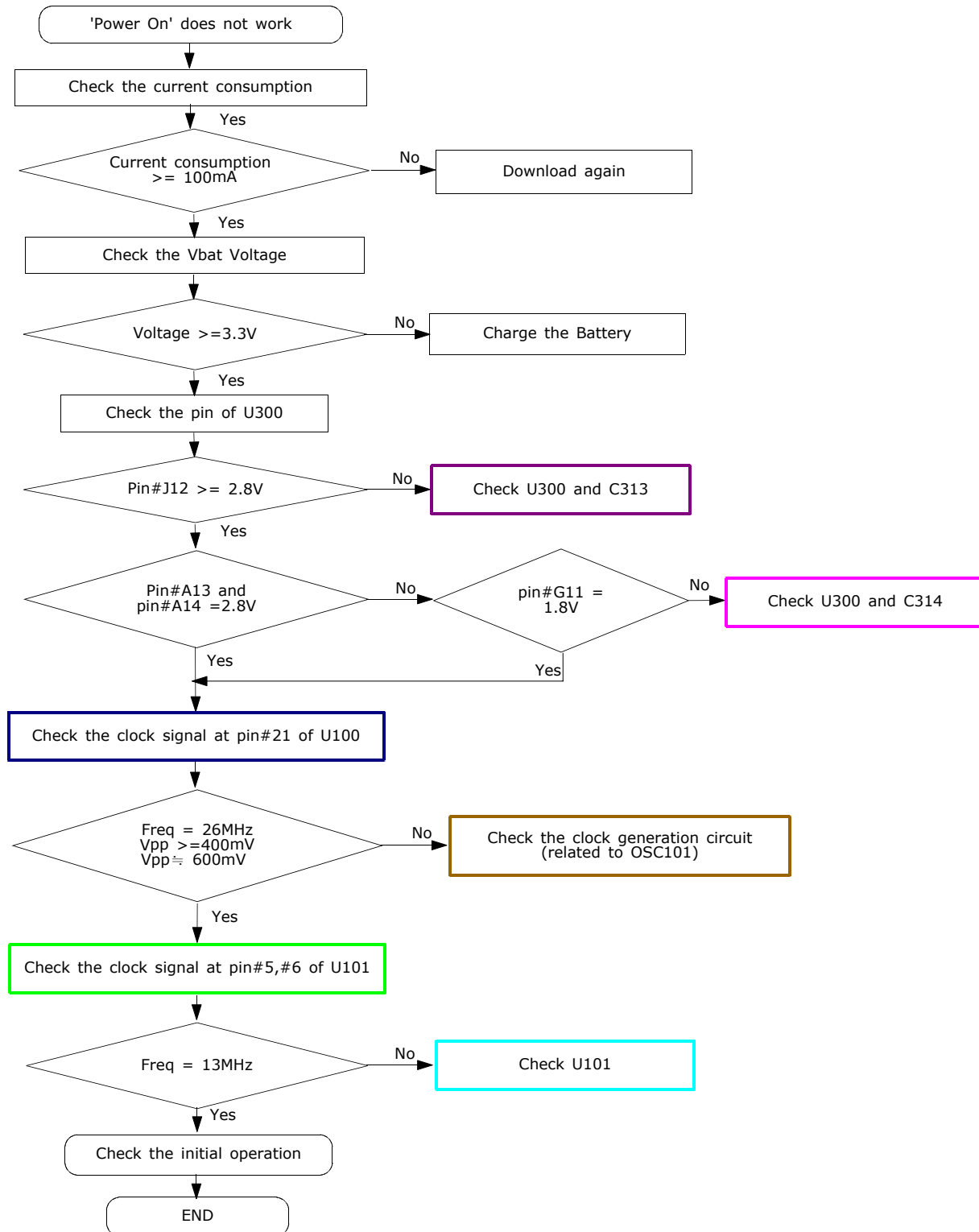
※ **Caution**

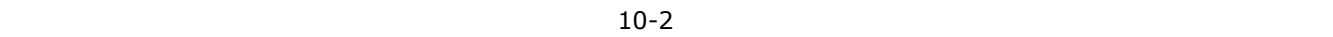
1) Be careful not to make scratch and molding damage!

10. Flow Chart of Troubleshooting

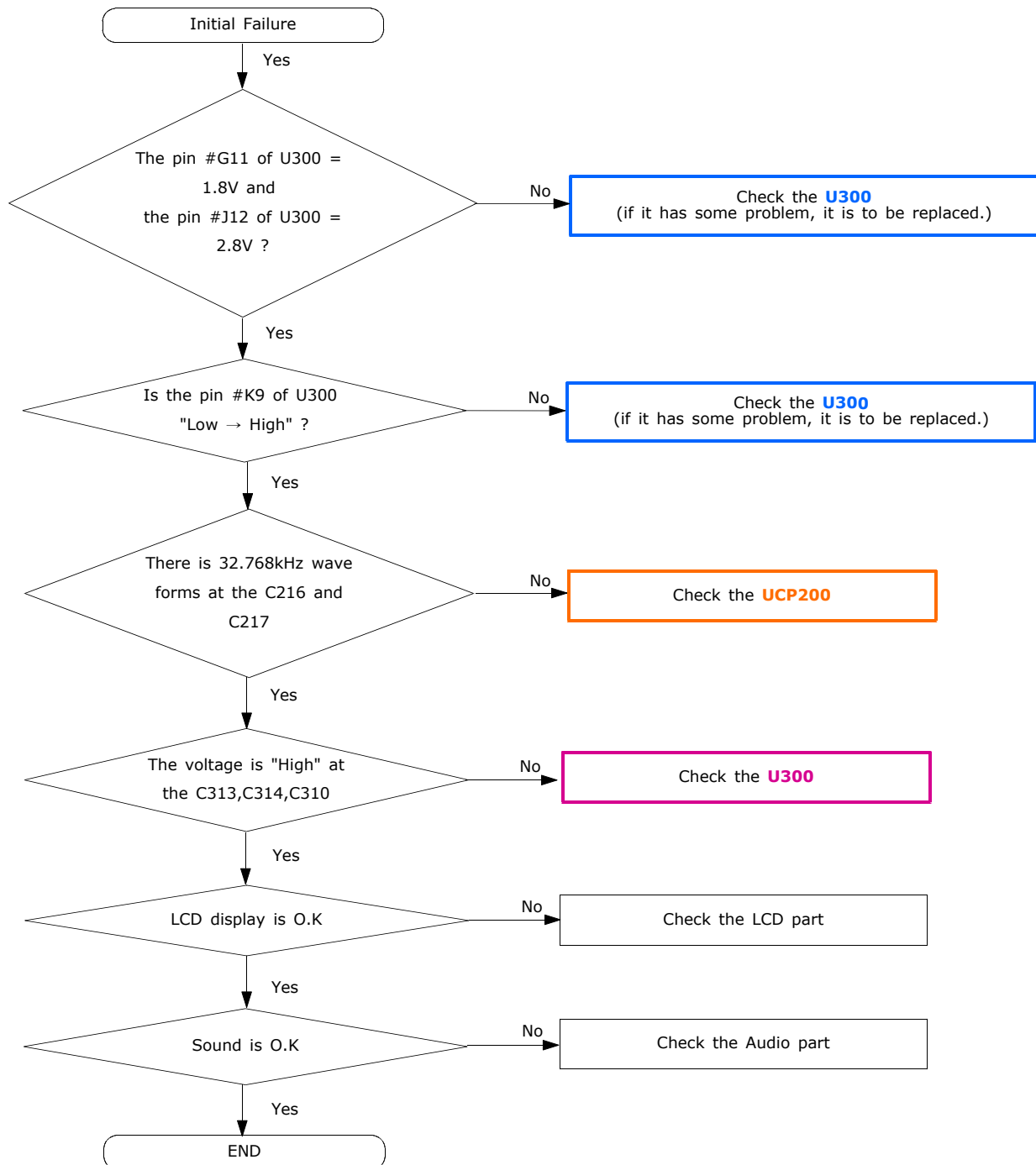
10-1.Baseband

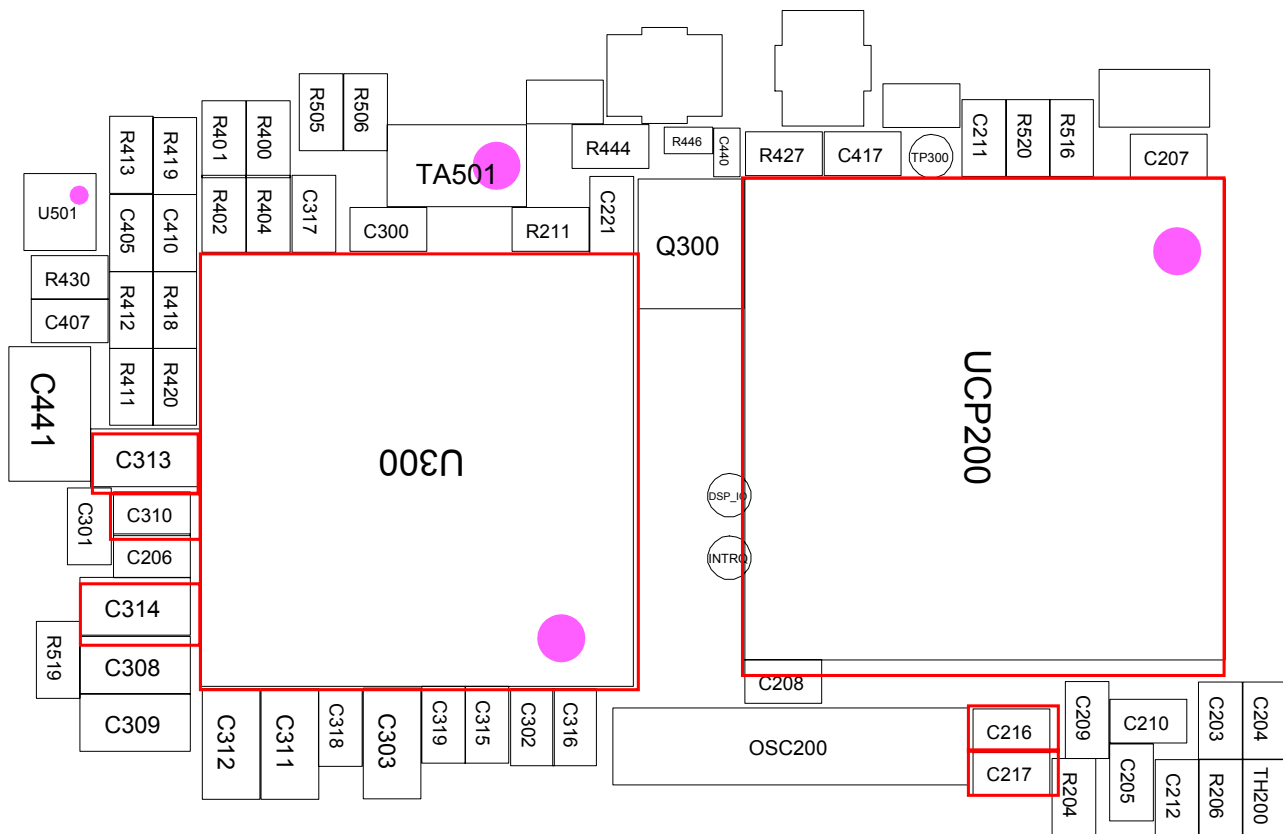
10-1-1. Power ON

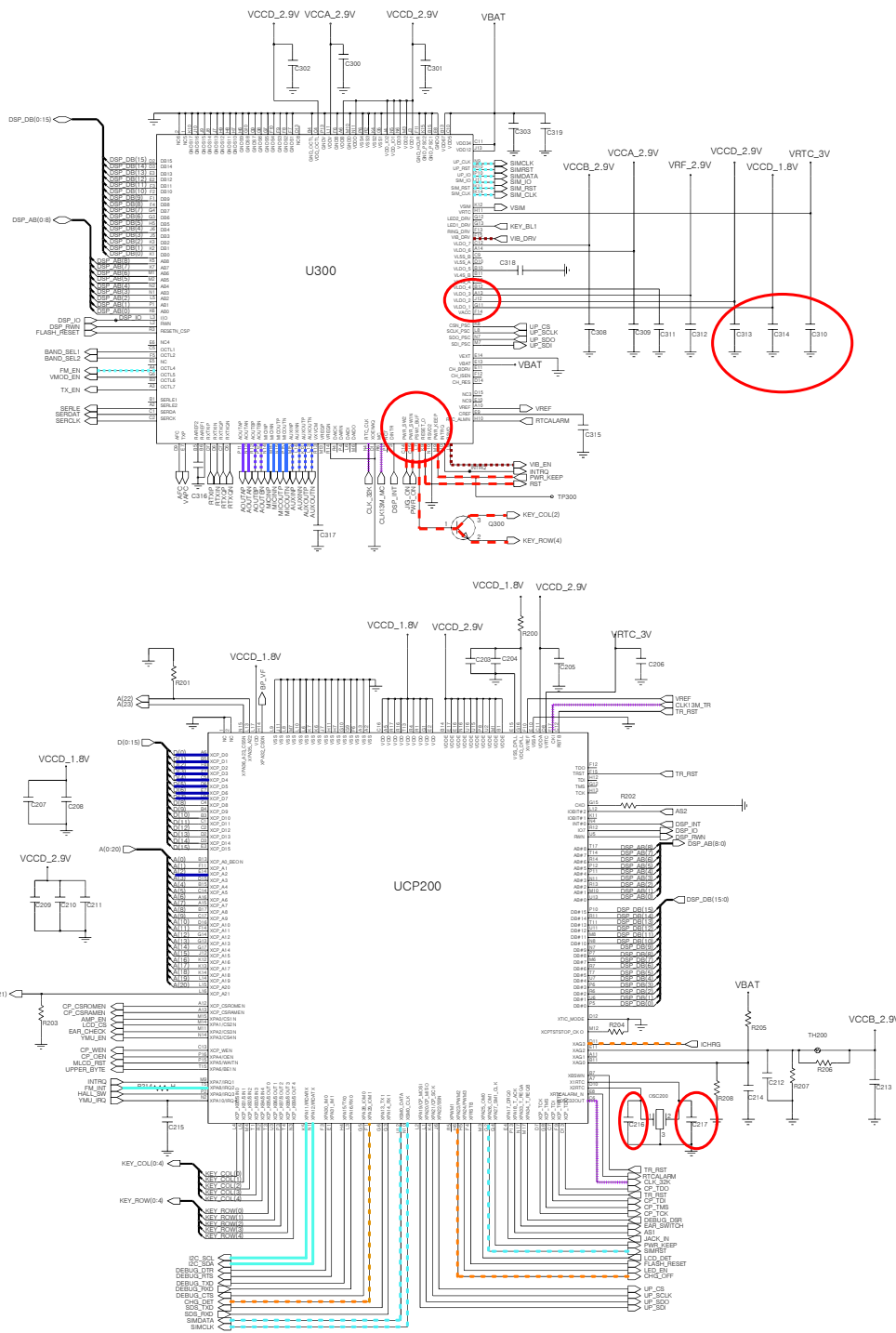




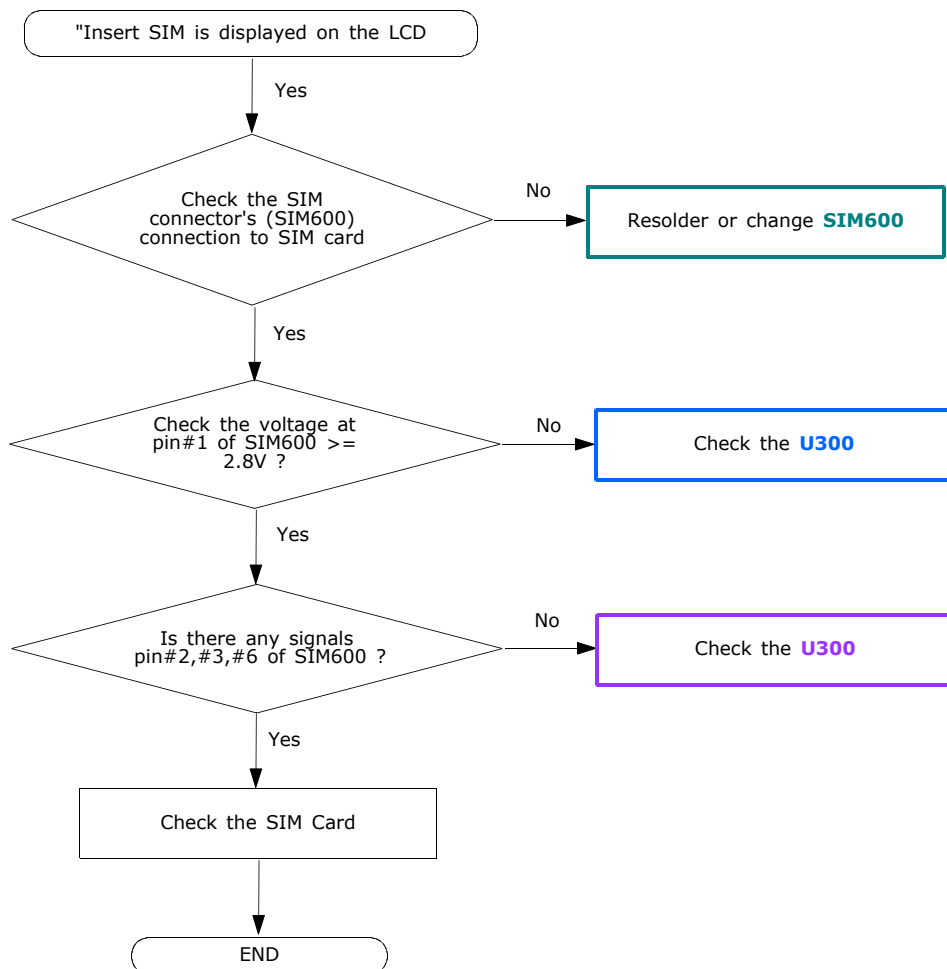
10-1-2. System Initial

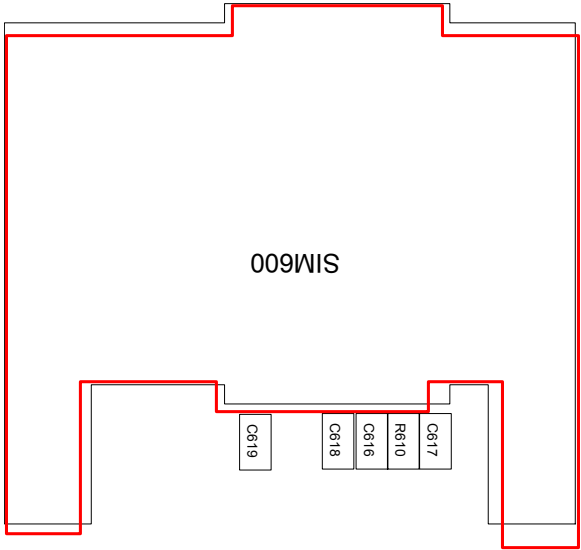




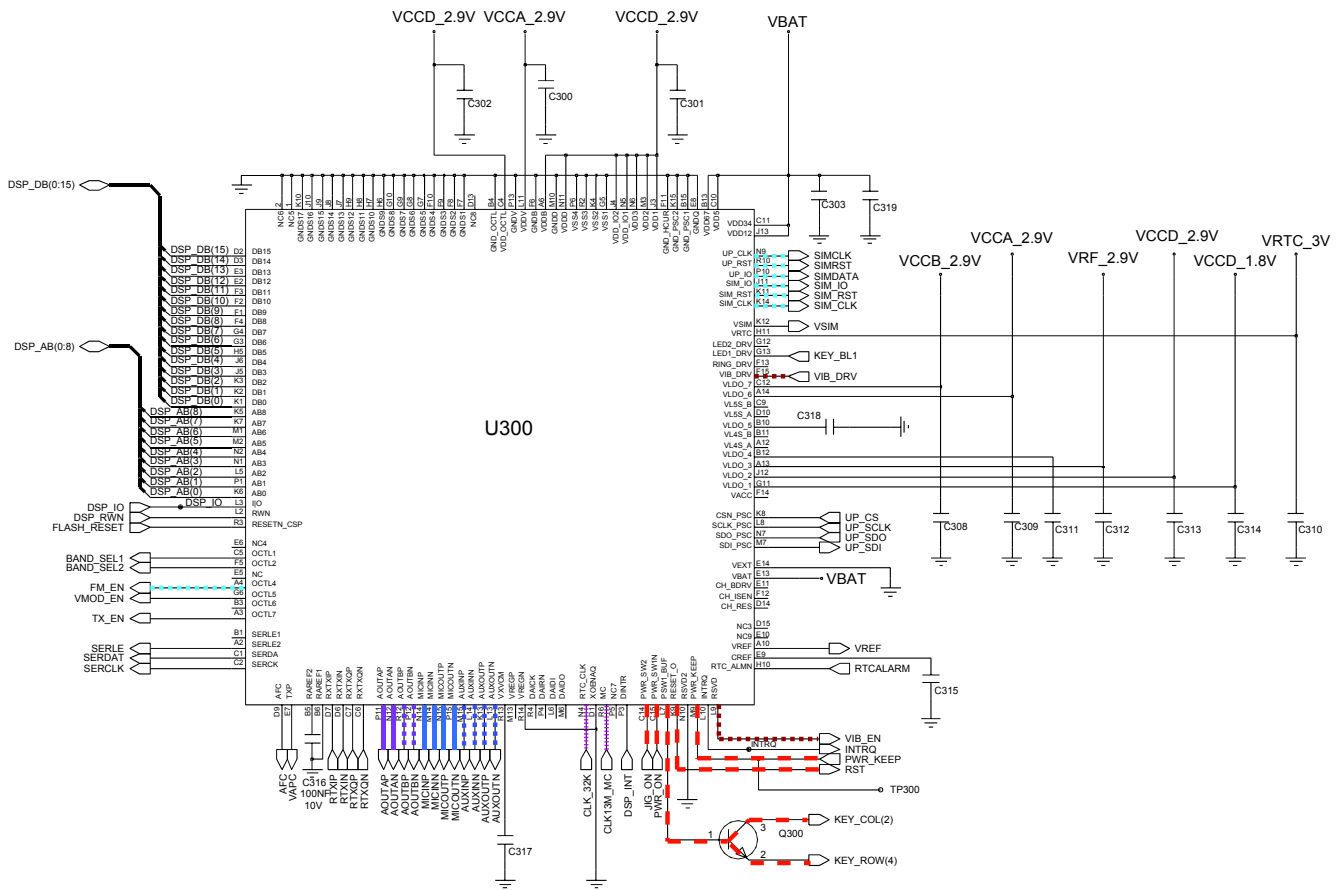
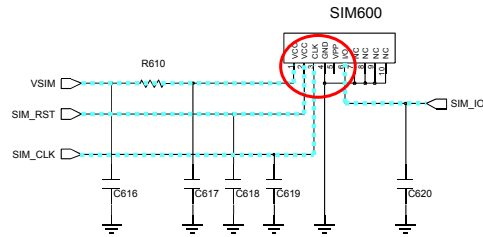
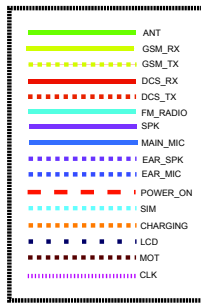


10-1-3. Sim Part

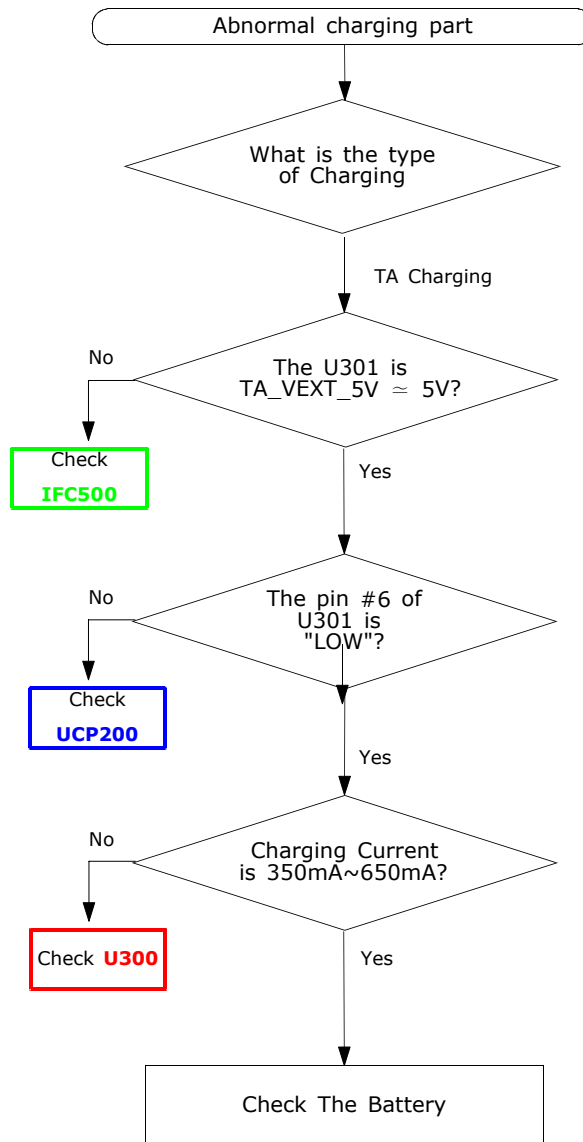


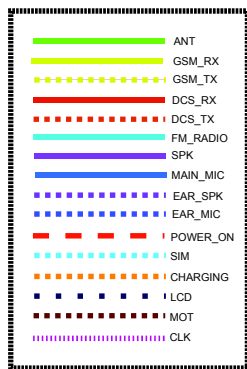


Flow Chart of Troubleshooting

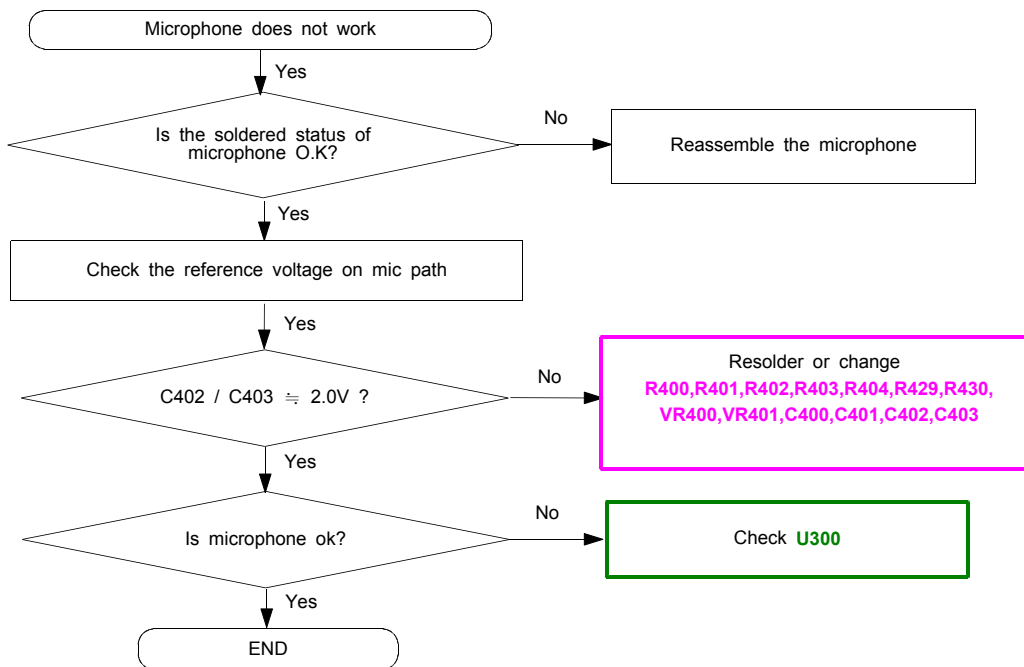


10-1-4. Charging Part

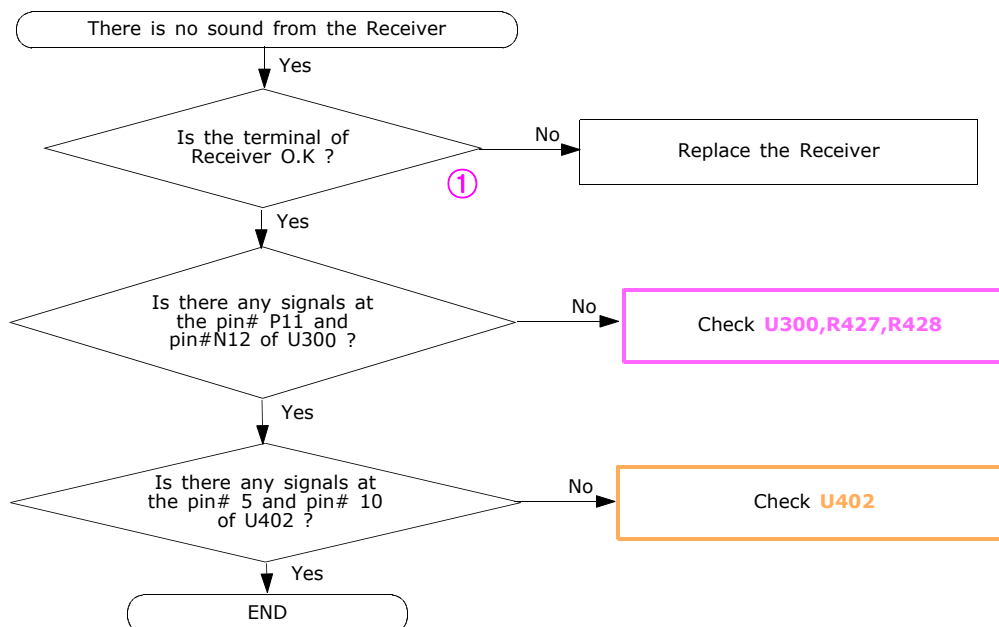




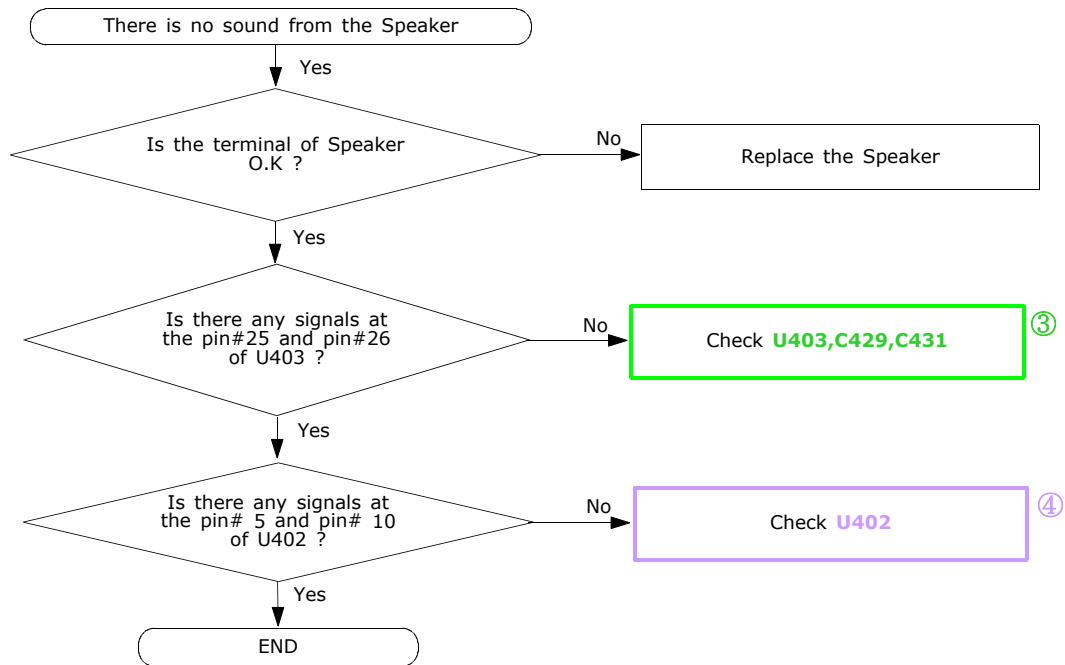
10-1-5. Microphone Part



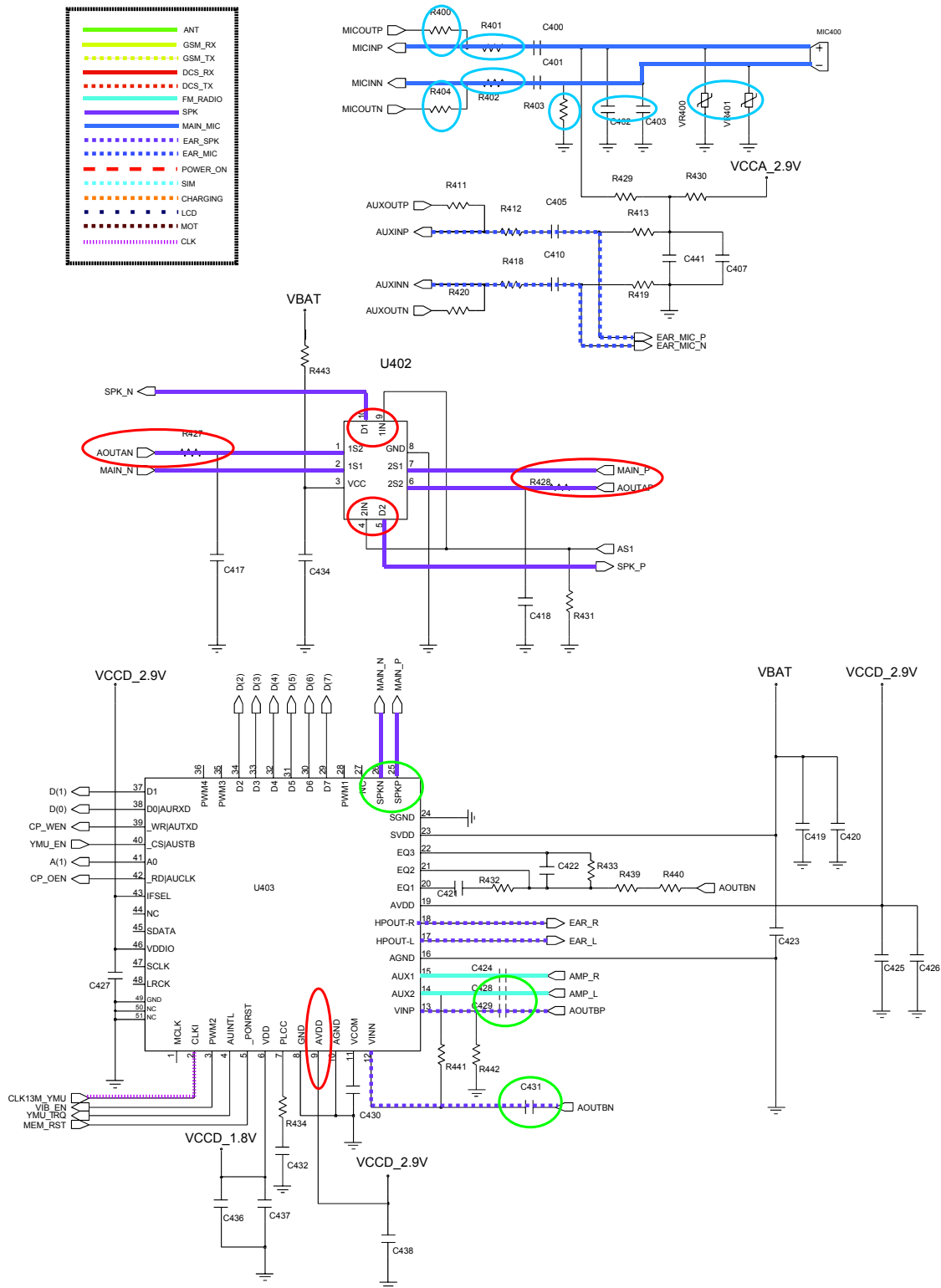
10-1-6. Receiver Part

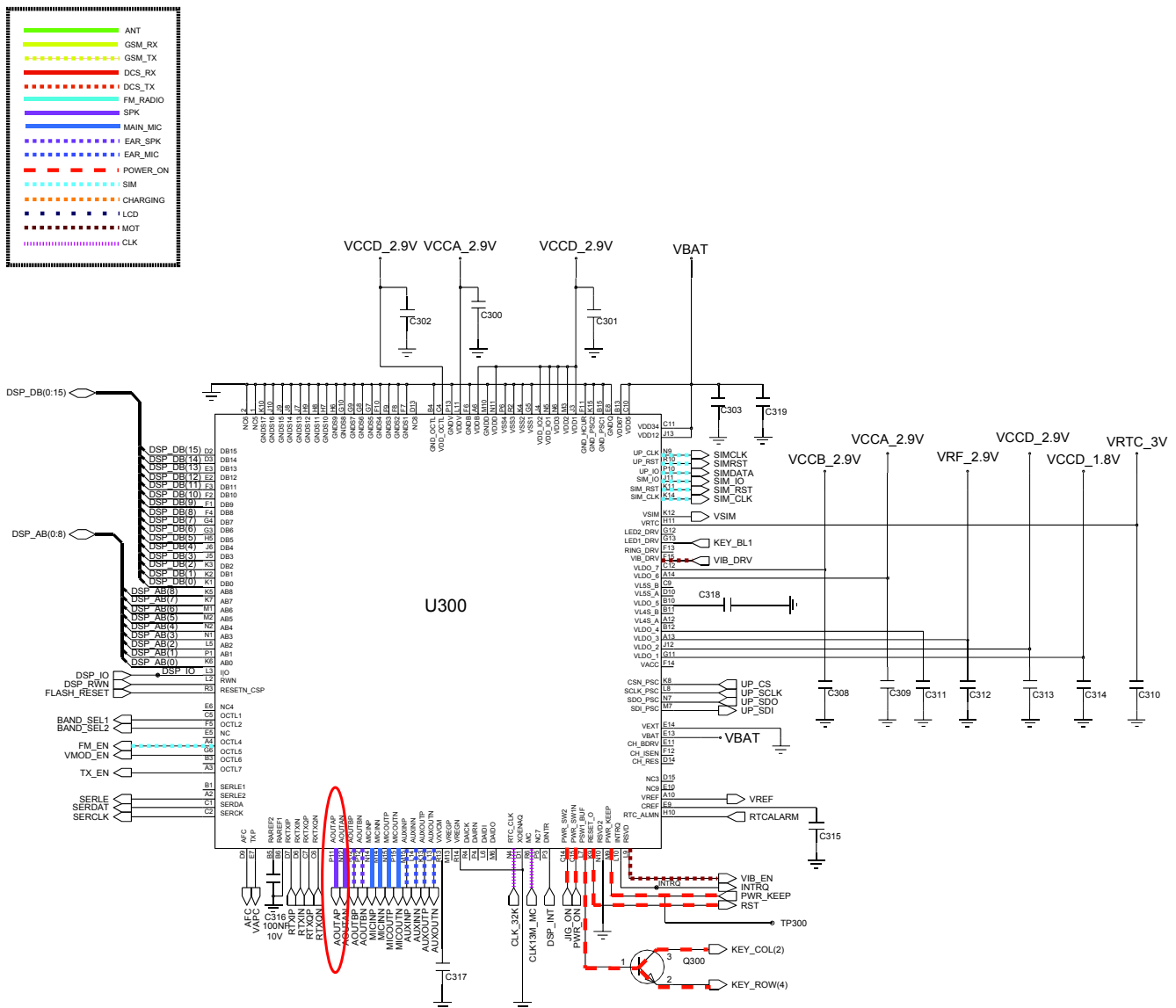


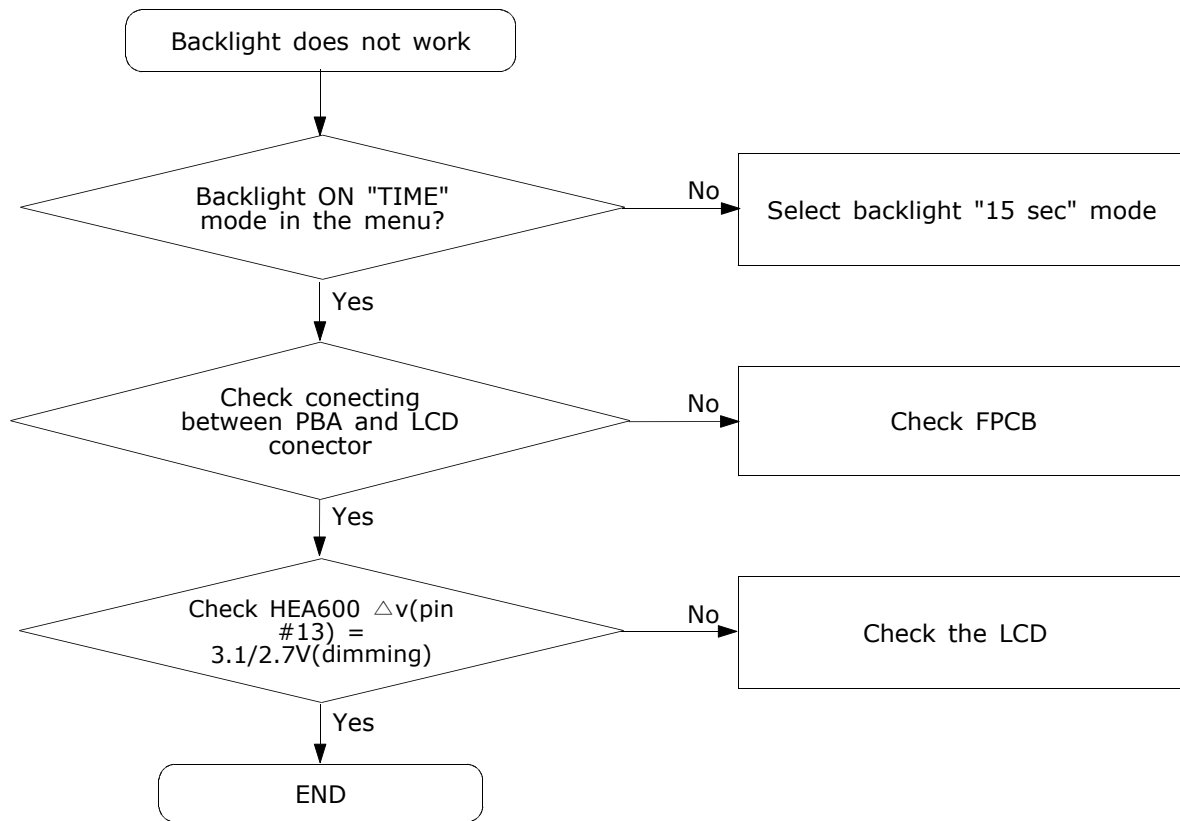
10-1-7. Speaker Part



Flow Chart of Troubleshooting

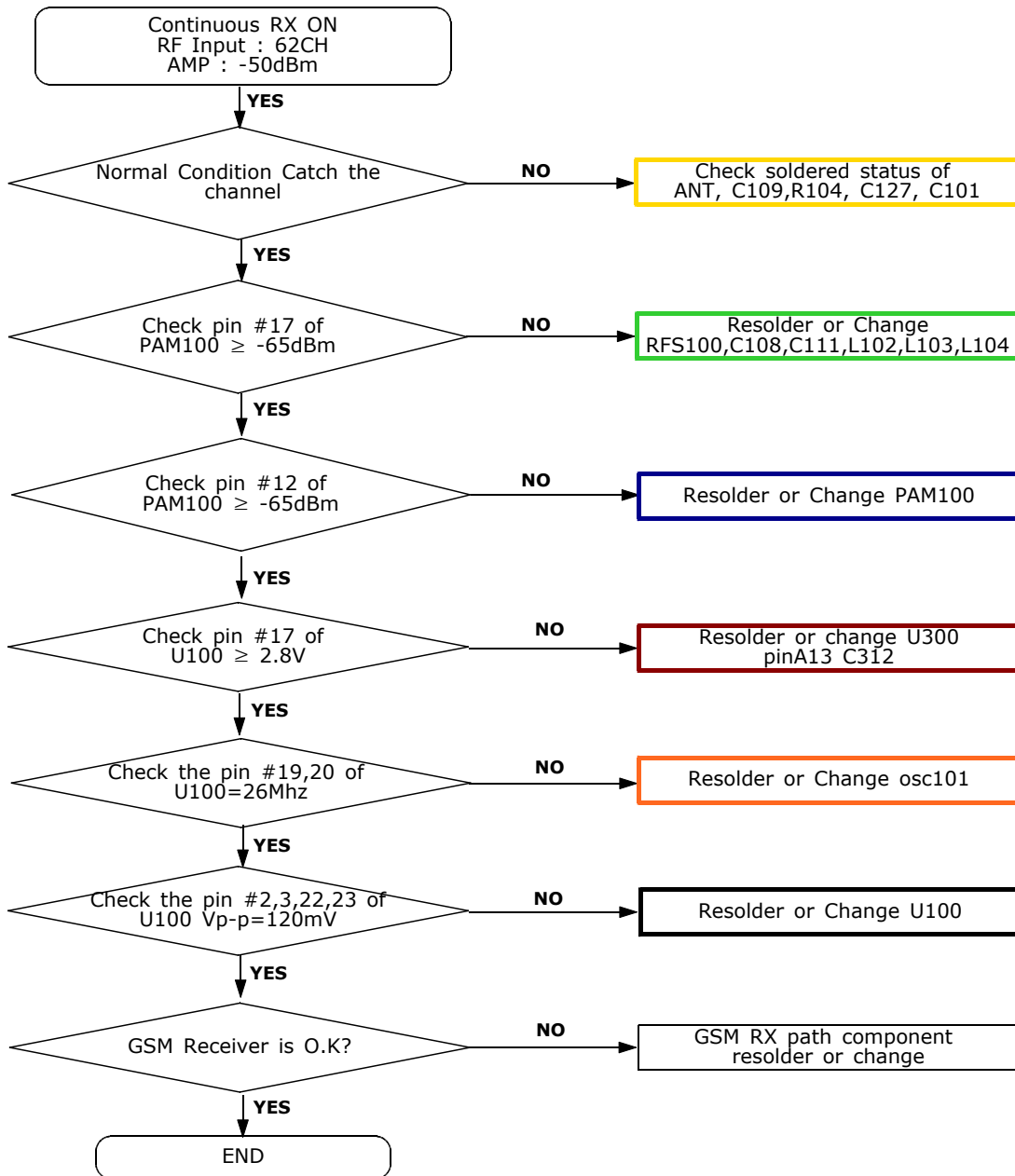




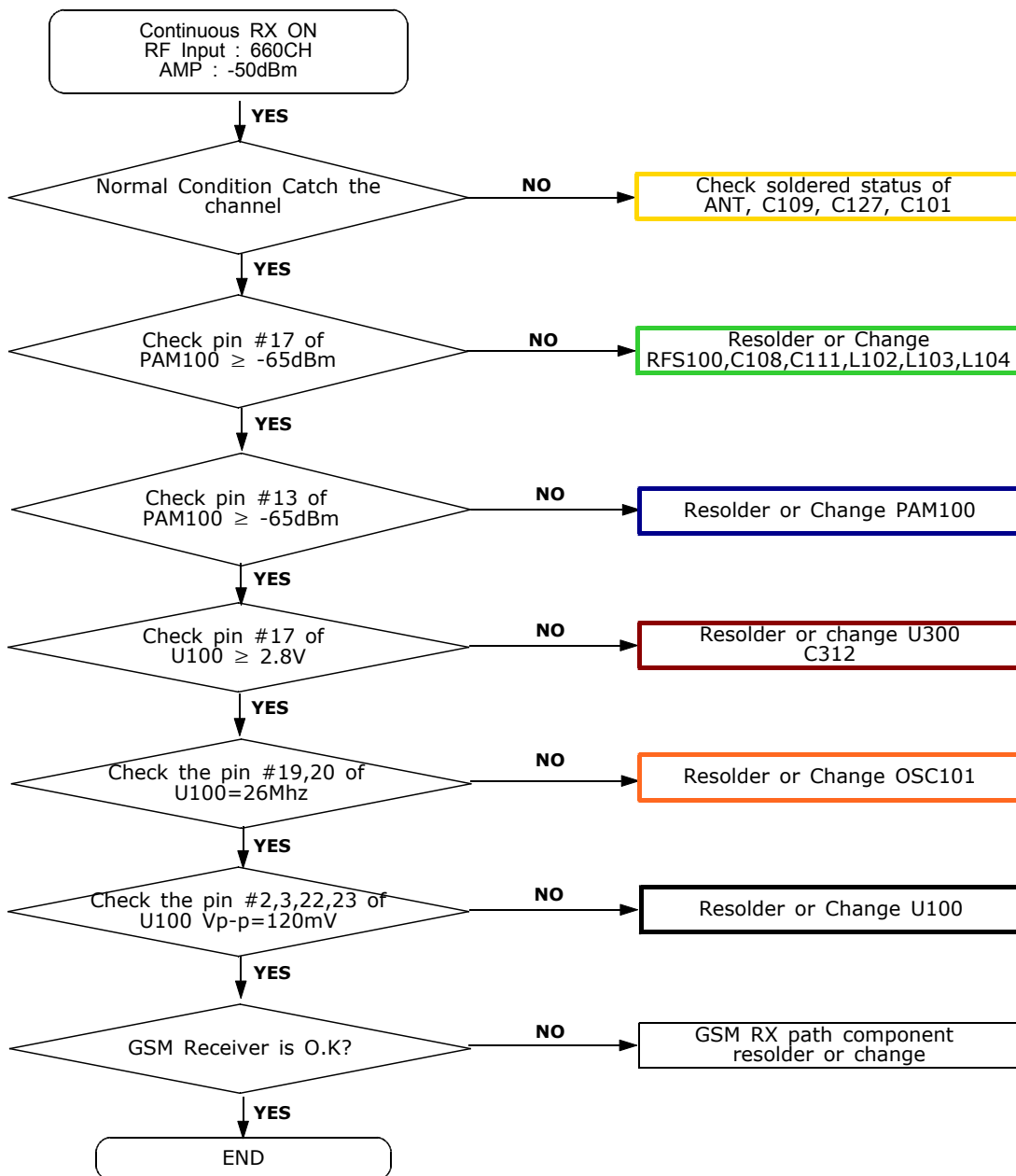
10-1-8. LCD

10-2.RF

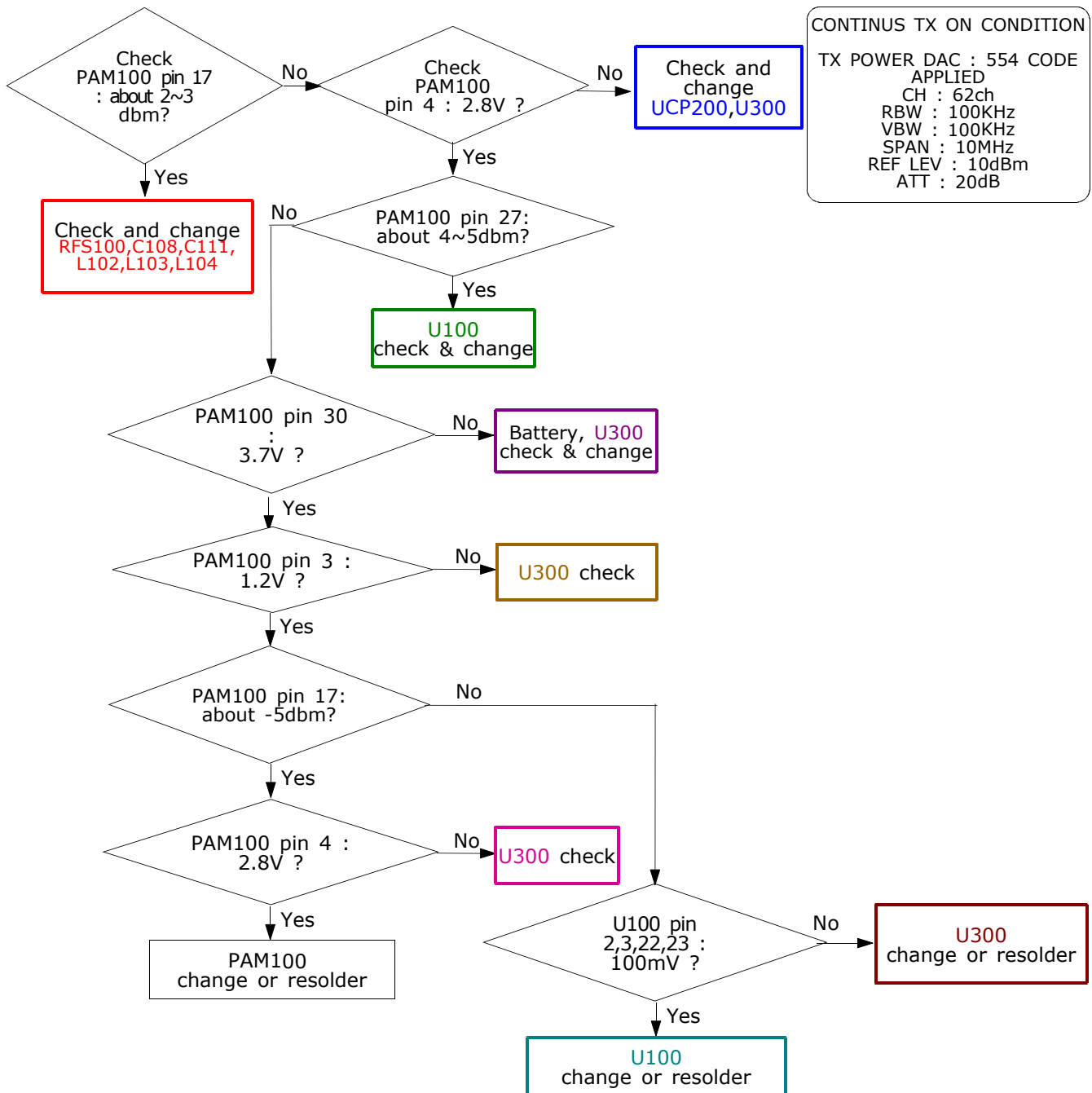
10-2-1. EGSM Rx



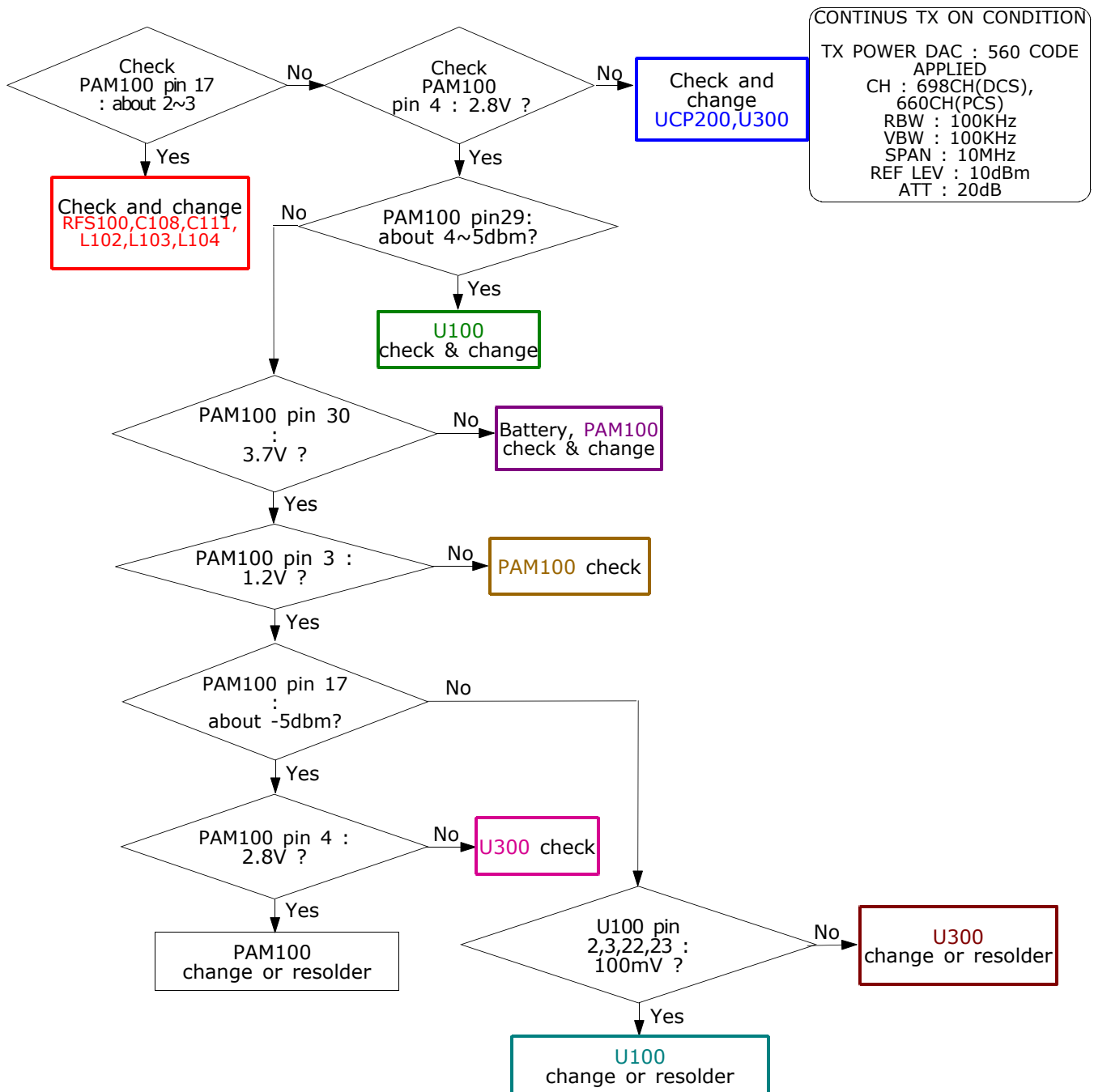
10-2-2. DCS Rx

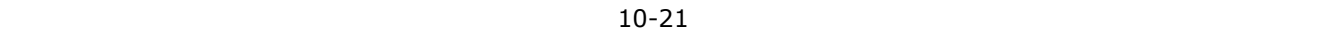


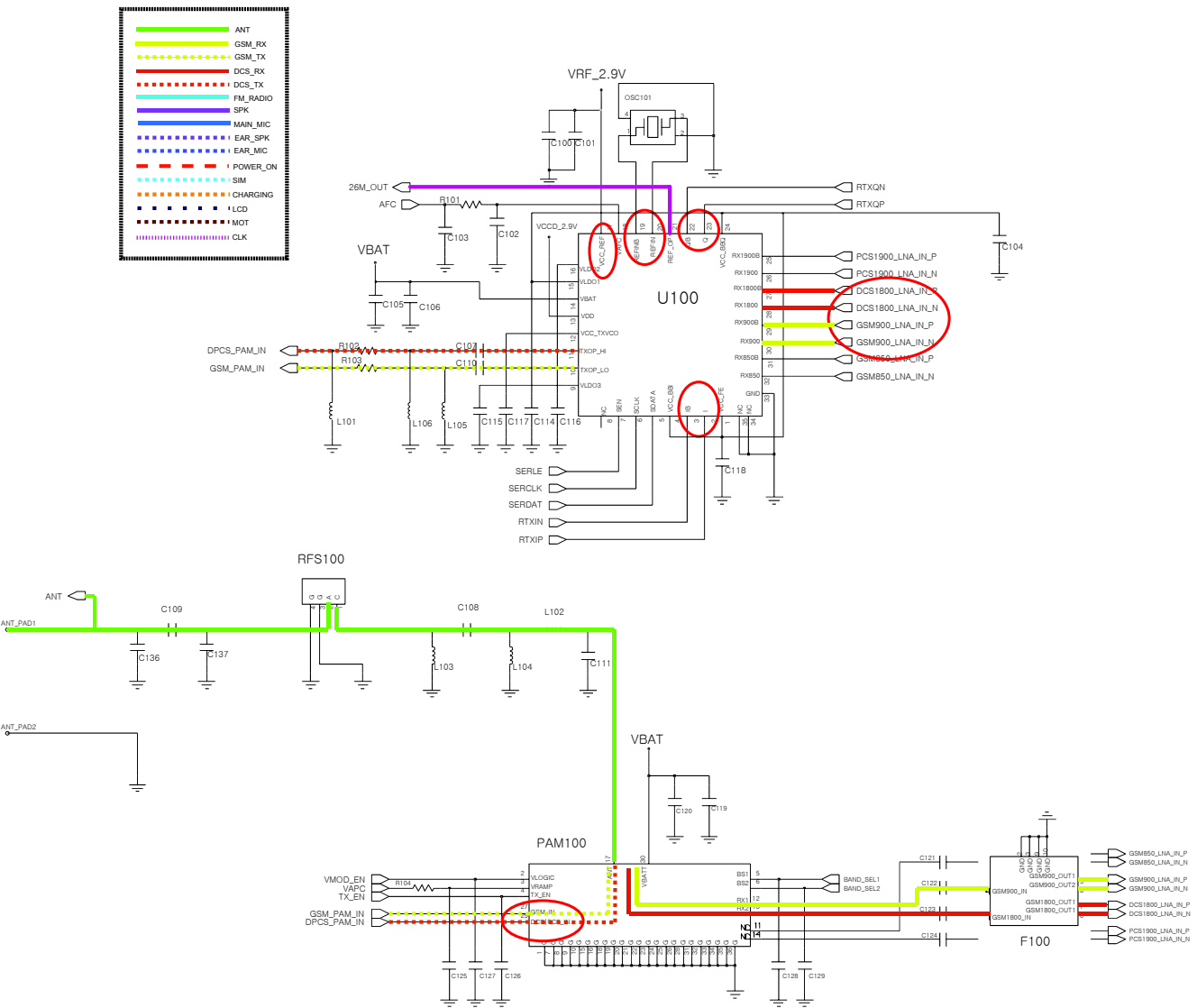
10-2-3. EGSM Tx



10-2-4. DCS Tx







4. Array course control



Test Jig (GH80-00865A)



Test Cable
(0.4M:GH39-00892A, 1.5M:GH39-00895A)



RF Test Cable (GH39-00985A)

Software Downloading

4-1. Downloading Binary Files

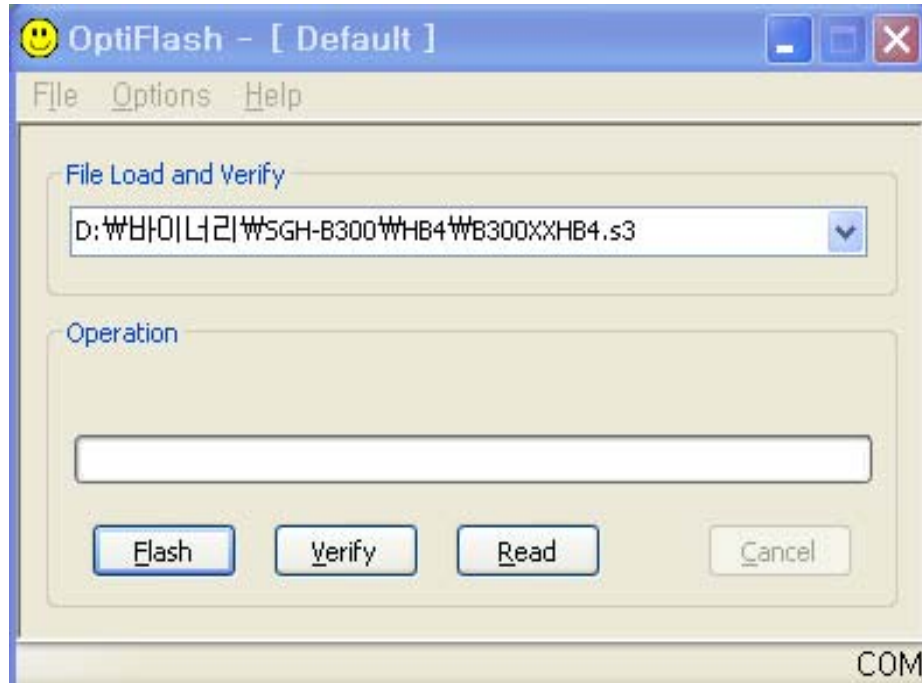
- Three binary files for downloading B300.
 - B300XXYY.s3 : Main source code binary.

4-2. Pre-requisite for Downloading

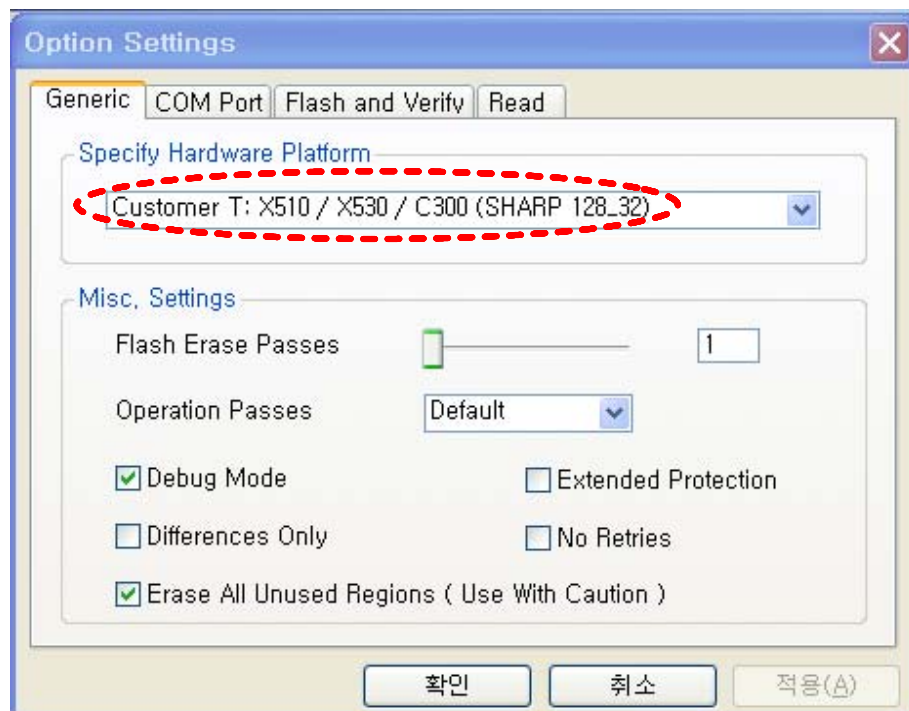
- Downloader Program([OptiFlash.exe](#))
- B300 Mobile Phone
- Data Cable
- Binary files

4-3. S/W Downloader Program

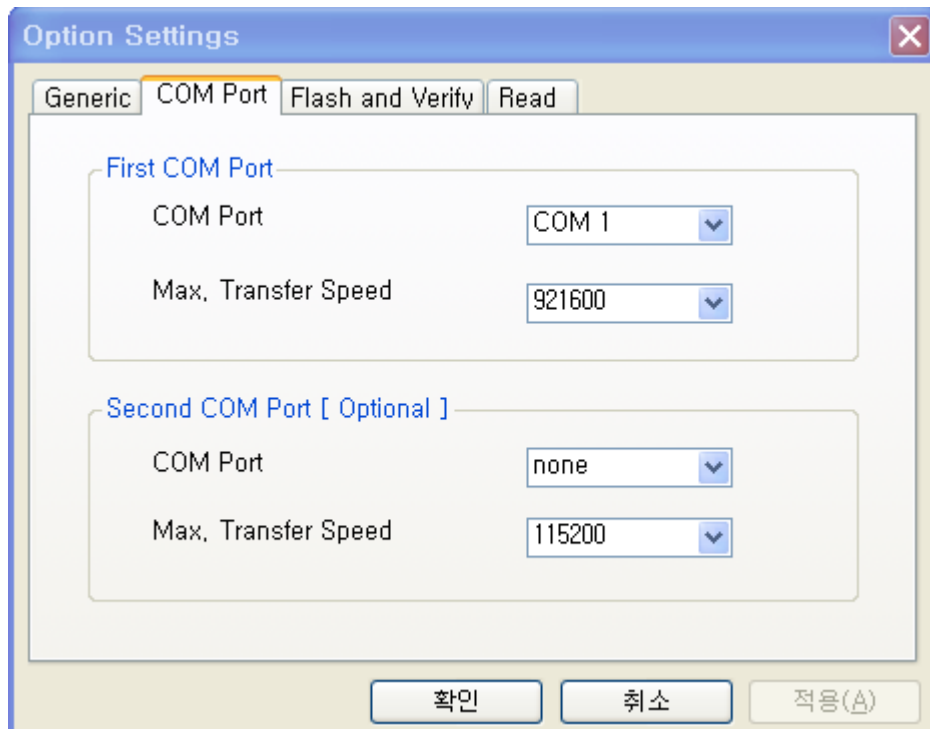
1. Load the binary download program by executing the “**OptiFlash.exe**”



2. Select the “**Options**” -> “**Settings**” -> “**Generic**” -> “**Specify hardware platform**”.
Choose hardware platform for the downloader file setting.
Set the everything else as the default values which are shown below



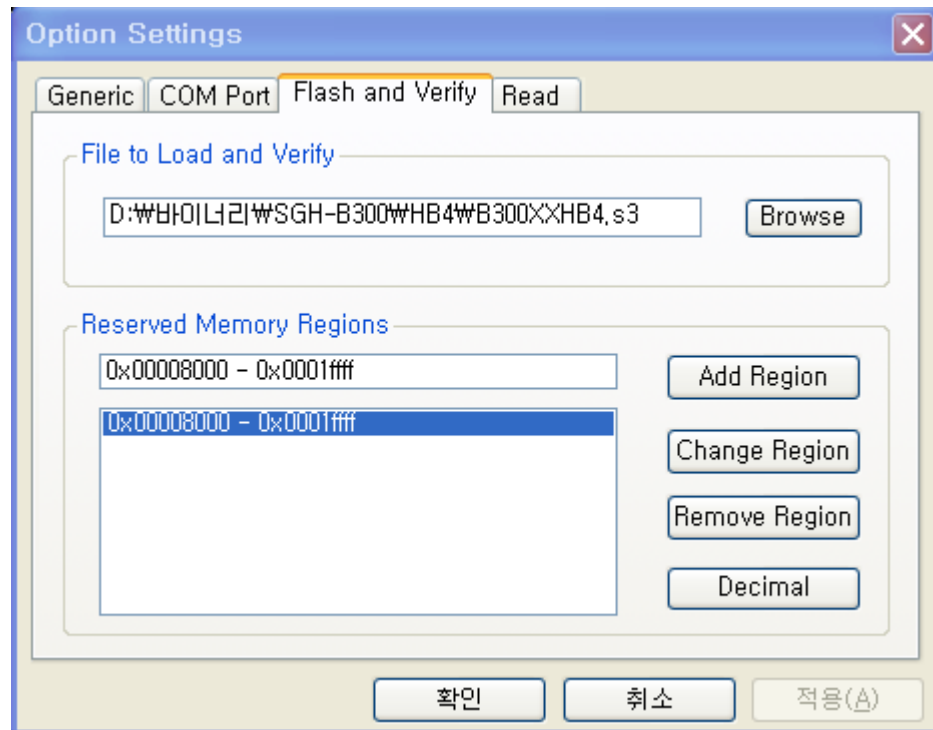
3. Select the **COM port** when the download cable is connected



Up to twelve ports are supported. Additionally you can select the maximum transfer speed OptiFlash will use to communicate with the phone. However, OptiFlash will use a slower speed if either the PC's or the phone's serial hardware is incapable of handling the selected speed

4. Select the **Flash&Verify** -> **Browse**

Set the directory path and choose the latest s/w binary, for example B300XXYY.s3", for the downloader binary setting.



Make sure that not to change the reserved memory regions.

**In case of B108 the reserved memory regions are :
-0x00008000 – 0x0001ffff**

5. Click “**OK**” button then press “**Flash**”.

(Before pressing ‘Flash’ button, push the button “*****” and ‘**END**’ at the same time. Then press ‘Flash’.)

Downloader will upload the binary file as below for the downloading.



6. When downloading is finished successfully, there is a “All is well” message.

7. After finishing downloading, Certain memory resets should be done to guarantee the normal performance.

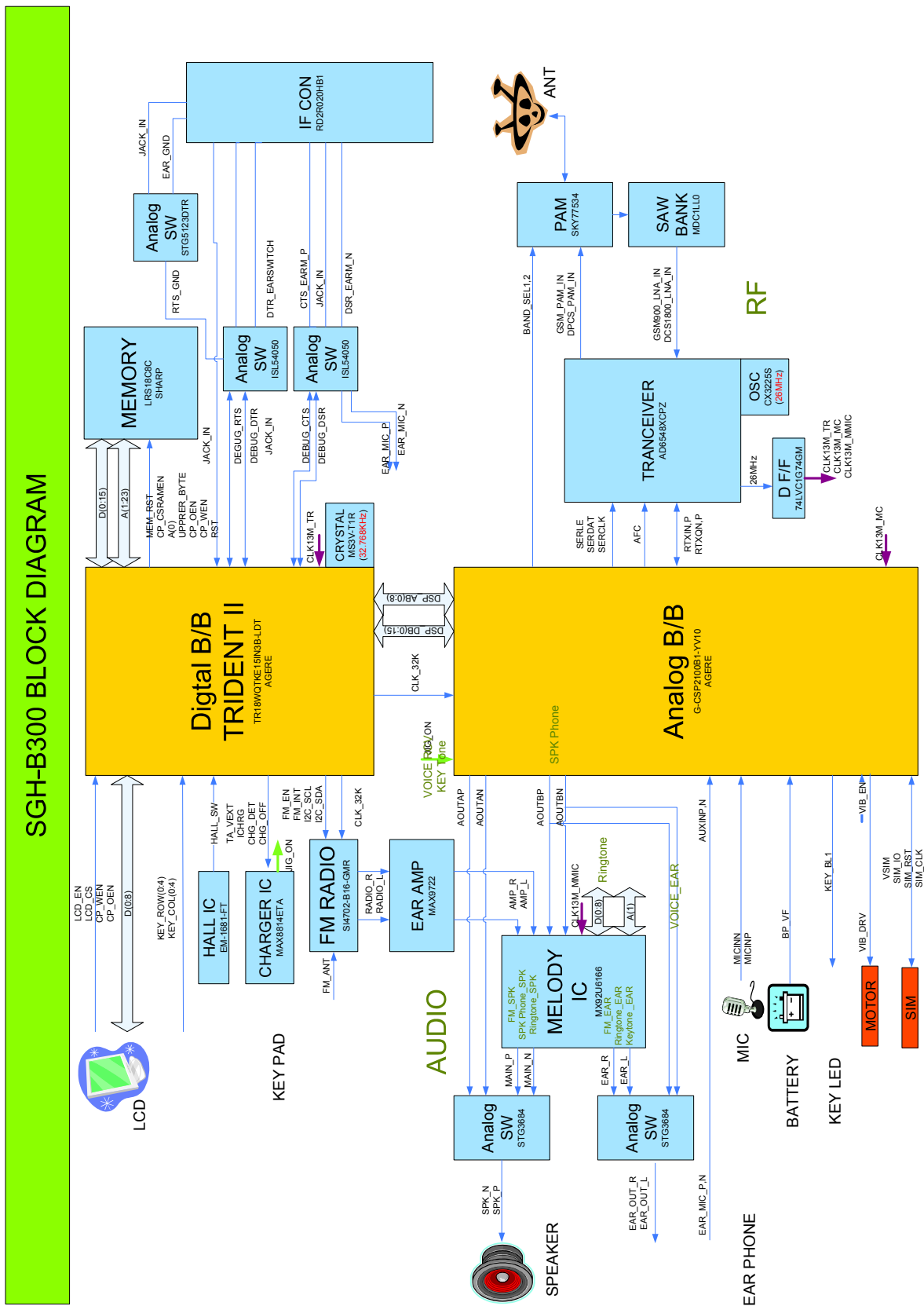
8. Confirm the downloaded version name and etc. :

***#1111#**

Full Reset :

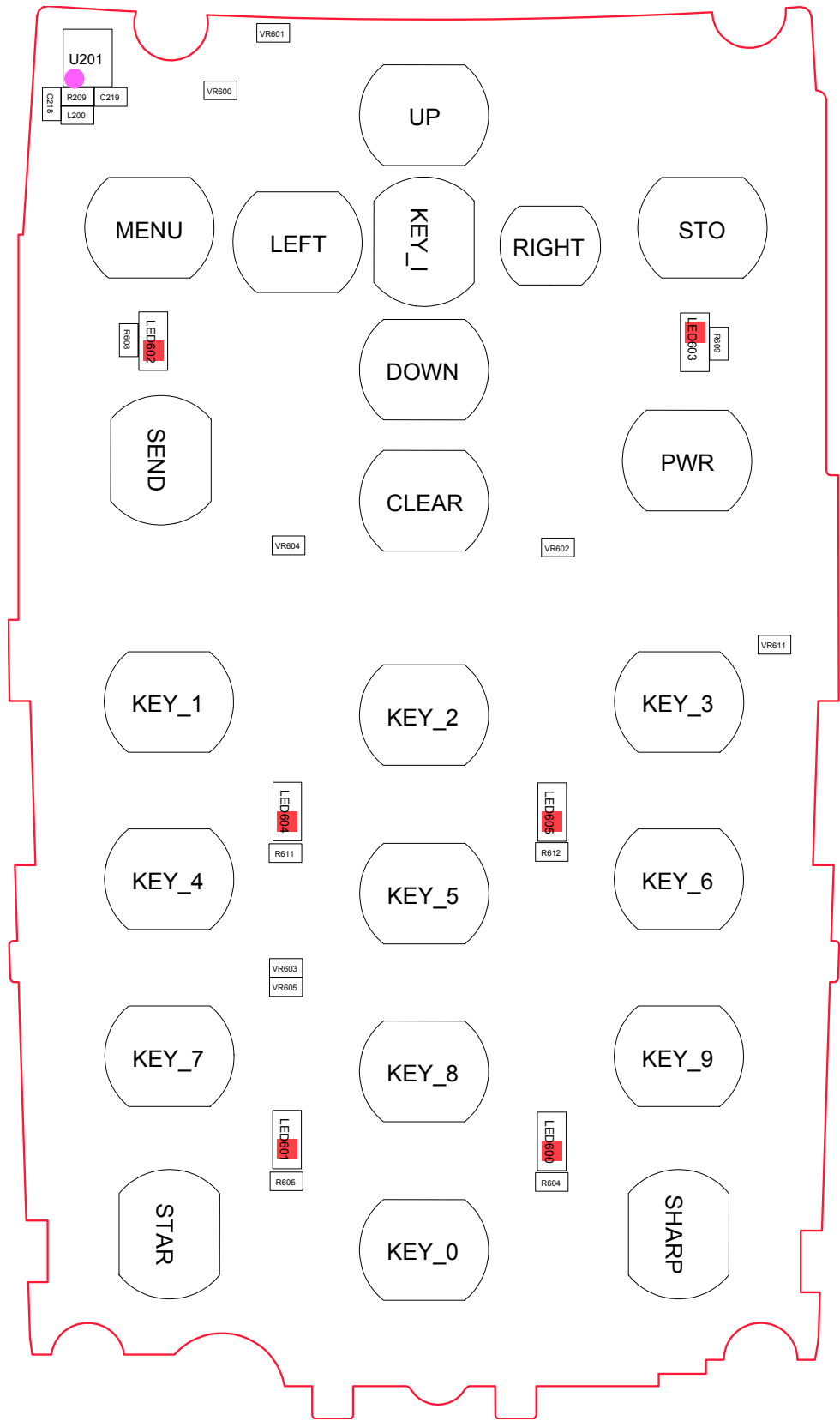
***2767*3855#**

8. Block Diagrams



9. PCB Diagrams





3. Product Function

Main Function

- Speed dial
- Phonebook memory status
- SDN(Service Dialling Numbers)
- Network services
- Read SMS or MMS messages
- Send SMS or MMS messages
- Voicemail
- Broadcast message
- MMS profile
- Wap browser
- FM Radio
- Java Games
- Menu shortcuts

11. Reference data

11-1. Reference Abbreviate

AAC: Advanced Audio Coding.

AVC : Advanced Video Coding.

BER : Bit Error Rate

BPSK: Binary Phase Shift Keying

CA : Conditional Access

CDM : Code Division Multiplexing

C/I : Carrier to Interference

DMB : Digital Multimedia Broadcasting

EN : European Standard

ES : Elementary Stream

ETSI: European Telecommunications Standards Institute

MPEG: Moving Picture Experts Group

PN : Pseudo-random Noise

PS : Pilot Symbol

QPSK: Quadrature Phase Shift Keying

RS : Reed-Solomon

SI : Service Information

TDM : Time Division Multiplexing

TS : Transport Stream

1. Safety Precautions

1-1. Repair Precaution

- Repair in Shield Box, during detailed tuning.
Take specially care of tuning or test,
because specipicty of cellular phone is sensitive for surrounding interference(RF noise).
- Be careful to use a kind of magnetic object or tool,
because performance of parts is damaged by the influence of manetic force.
- Surely use a standard screwdriver when you disassemble this product,
otherwise screw will be worn away.
- Use a thicken twisted wire when you measure level.
A thicken twisted wire has low resistance, therefore error of measurement is few.
- Repair after separate Test Pack and Set because for short danger (for example an
overcurrent and furious flames of parts etc) when you repair board in condition of
connecting Test Pack and tuning on.
- Take specially care of soldering, because Land of PCB is small and weak in heat.
- Surely tune on/off while using AC power plug, because a repair of battery charger is
dangerous when tuning ON/OFF PBA and Connector after disassembling charger.
- Don't use as you pleases after change other material than replacement registered on SEC
System.
Otherwise engineer in charge isn't charged with problem that you don't keep this rules.

1-2. ESD(Electrostatically Sensitive Devices) Precaution

Several semiconductor may be damaged easily by static electricity. Such parts are called by ESD(Electrostatically Sensitive Devices), for example IC,BGA chip etc. Read Precaution below. You can prevent from ESD damage by static electricity.

- Remove static electricity remained your body before you touch semiconductor or parts with semiconductor. There are ways that you touch an earthed place or wear static electricity prevention string on wrist.
- Use earthed soldering steel when you connect or disconnect ESD.
- Use soldering removing tool to break static electricity. , otherwise ESD will be damaged by static electricity.
- Don't unpack until you set up ESD on product. Because most of ESD are packed by box and aluminum plate to have conductive power,they are prevented from static electricity.
- You must maintain electric contact between ESD and place due to be set up until ESD is connected completely to the proper place or a circuit board.

6. MAIN Electrical Parts List

SEC CODE	Design LOC	Discription
0403-001547	ZD502	DIODE-ZENER
0406-001241	ZD500	DIODE-TVS
0406-001241	ZD501	DIODE-TVS
0504-000168	Q300	TR-DIGITAL
0601-002361	LED600	LED
0601-002361	LED601	LED
0601-002361	LED602	LED
0601-002361	LED603	LED
0601-002361	LED604	LED
0601-002361	LED605	LED
0801-003206	U101	IC-CMOS LOGIC
1001-001428	U402	IC-ANALOG MULTIPLEX
1001-001428	U404	IC-ANALOG MULTIPLEX
1001-001428	U500	IC-ANALOG MULTIPLEX
1001-001428	U502	IC-ANALOG MULTIPLEX
1001-001488	U501	IC-ANALOG SWITCH
1009-001020	U201	IC-HALL EFFECT S/W
1108-000111	UME200	IC-MCP
1201-002180	U401	IC-AUDIO AMP
1201-002731	PAM100	IC-POWER AMP
1203-003897	U300	IC-POWER SUPERVISOR
1203-005005	U301	IC-BATTERY
1204-002700	U400	IC-TUNER
1204-002783	U403	IC-SOUND GENERATOR
1205-003098	U100	IC-TRANSCIEVER
1205-003412	UCP200	IC-MODEM
1404-001165	TH200	THERMISTOR-NTC
1405-001082	VR500	VARISTOR
1405-001082	VR501	VARISTOR
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2007-000160	R433	R-CHIP
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2007-009408	R403	R-CHIP
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2203-000233	C404	C-CER,CHIP
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2203-000254	C105	C-CER,CHIP
2203-000254	C204	C-CER,CHIP
2203-000254	C207	C-CER,CHIP
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2203-000254	C210	C-CER,CHIP
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2203-000359	C422	C-CER,CHIP
2203-000386	C130	C-CER,CHIP
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SEC CODE	Design LOC	Discription
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2203-000679	C203	C-CER,CHIP
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2203-000812	C612	C-CER,CHIP
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2203-000812	C615	C-CER,CHIP
2203-000812	C618	C-CER,CHIP
2203-000812	C619	C-CER,CHIP
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2203-000854	C103	C-CER,CHIP
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2203-000940	C616	C-CER,CHIP
2203-000995	C108	C-CER,CHIP
2203-000995	C110	C-CER,CHIP
2203-000995	C219	C-CER,CHIP

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2203-002668	C107	C-CER,CHIP
2203-005052	C113	C-CER,CHIP
2203-005056	C109	C-CER,CHIP
2203-005065	C308	C-CER,CHIP
2203-005065	C309	C-CER,CHIP
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2203-005993	C405	C-CER,CHIP
2203-005993	C410	C-CER,CHIP
2203-006047	C115	C-CER,CHIP

SEC CODE	Design LOC	Discription
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2203-006123	C403	C-CER,CHIP
2203-006137	C206	C-CER,CHIP
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2203-006137	C315	C-CER,CHIP
2203-006137	C421	C-CER,CHIP
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2203-006257	C318	C-CER,CHIP
2203-006257	C420	C-CER,CHIP
2203-006257	C617	C-CER,CHIP
2203-006260	C116	C-CER,CHIP
2203-006260	C208	C-CER,CHIP
2203-006260	C211	C-CER,CHIP
2203-006324	C303	C-CER,CHIP
2203-006324	C304	C-CER,CHIP
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2203-007143	C400	C-CER,CHIP
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2404-001393	TA502	C-TA,CHIP
2404-001406	TA500	C-TA,CHIP
2703-001236	L108	INDUCTOR-SMD
2703-001751	L106	INDUCTOR-SMD
2703-002178	L503	INDUCTOR-SMD
2703-002208	L102	INDUCTOR-SMD
2703-002269	L103	INDUCTOR-SMD
2801-004353	OSC200	CRYSTAL-SMD
2801-004689	OSC101	CRYSTAL-SMD
2904-001811	F100	FILTER-SAW
3301-001342	L110	BEAD-SMD
3301-001885	L200	BEAD-SMD
3301-001885	L501	BEAD-SMD
3301-001885	L502	BEAD-SMD
3705-001503	RFS100	CONNECTOR-COAXIAL
3709-001384	SIM600	CONNECTOR-CARD EDGE
3710-002499	IFC500	SOCKET-INTERFACE
3711-005954	HEA600	HEADER-BOARD TO BOARD
3711-006228	BTC500	HEADER-BATTERY

Please consult the GSPN website (Samsung Portal) for the most recent version of the product's part list.

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